



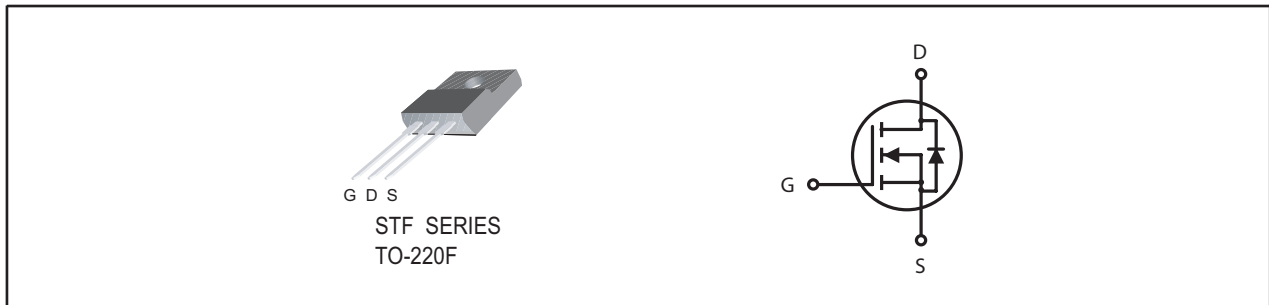
## N-Channel Enhancement Mode Field Effect Transistor

### PRODUCT SUMMARY

| V <sub>DSS</sub> | I <sub>D</sub> | R <sub>DS(ON)</sub> (mΩ) Typ |
|------------------|----------------|------------------------------|
| 60V              | 32A            | 15 @ V <sub>GS</sub> =10V    |

### FEATURES

- Super high dense cell design for low R<sub>DS(ON)</sub>.
- Rugged and reliable.
- TO-220F Package.



### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub>=25°C unless otherwise noted)

| Symbol                            | Parameter  | Limit                | Units |
|-----------------------------------|--|----------------------|-------|
| V <sub>DS</sub>                   | Drain-Source Voltage                             | 60                   | V     |
| V <sub>GS</sub>                   | Gate-Source Voltage                              | ±20                  | V     |
| I <sub>D</sub>                    | Drain Current-Continuous <sup>a</sup>            | T <sub>C</sub> =25°C | 32    |
|                                   |  | T <sub>C</sub> =70°C | 26.8  |
| I <sub>DM</sub>                   | -Pulsed <sup>b</sup>                             | 95                   | A     |
| E <sub>AS</sub>                   | Avalanche Energy <sup>d</sup>                    | 144                  | mJ    |
| P <sub>D</sub>                    | Maximum Power Dissipation <sup>a</sup>           | T <sub>C</sub> =25°C | 30    |
|                                   |  | T <sub>C</sub> =70°C | 21    |
| T <sub>J</sub> , T <sub>STG</sub> | Operating Junction and Storage Temperature Range | -55 to 175           | °C    |

### THERMAL CHARACTERISTICS

|                   |   |    |      |
|-------------------|---|----|------|
| R <sub>θ JC</sub> | Thermal Resistance, Junction-to-Case    | 5  | °C/W |
| R <sub>θ JA</sub> | Thermal Resistance, Junction-to-Ambient | 65 | °C/W |

# STP60L60F

Ver 1.0

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25°C unless otherwise noted)

| Symbol   | Parameter                        | Conditions   | Min | Typ  | Max  | Units |
|--|----------------------------------|--|-----|------|------|-------|
| <b>OFF CHARACTERISTICS</b>   |                                  |  |     |      |      |       |
| BV <sub>DSS</sub>  | Drain-Source Breakdown Voltage   | V <sub>GS</sub> =0V , I <sub>D</sub> =250uA                        | 60  |      |      | V     |
| I <sub>DSS</sub>   | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =48V , V <sub>GS</sub> =0V                         |     |      | 1    | uA    |
| I <sub>GSS</sub>   | Gate-Body Leakage Current        | V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V                       |     |      | ±100 | nA    |
| <b>ON CHARACTERISTICS</b>  |                                  |  |     |      |      |       |
| V <sub>GS(th)</sub>  | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA           | 2   | 2.8  | 4    | V     |
| R <sub>DS(ON)</sub>  | Drain-Source On-State Resistance | V <sub>GS</sub> =10V , I <sub>D</sub> =16A                         |     | 15   | 19   | m ohm |
| g <sub>FS</sub>  | Forward Transconductance         | V <sub>DS</sub> =20V , I <sub>D</sub> =16A                         |     | 25   |      | S     |
| <b>DYNAMIC CHARACTERISTICS <sup>c</sup></b>                                    |                                  |  |     |      |      |       |
| C <sub>ISS</sub>   | Input Capacitance                | V <sub>DS</sub> =25V, V <sub>GS</sub> =0V<br>f=1.0MHz              |     | 2300 |      | pF    |
| C <sub>OSS</sub>   | Output Capacitance               |  |     | 142  |      | pF    |
| C <sub>RSS</sub>   | Reverse Transfer Capacitance     |  |     | 108  |      | pF    |
| <b>SWITCHING CHARACTERISTICS <sup>c</sup></b>                                  |                                  |  |     |      |      |       |
| t <sub>D(ON)</sub>   | Turn-On Delay Time               | V <sub>DD</sub> =30V<br>I <sub>D</sub> =1A                         |     | 63   |      | ns    |
| t <sub>r</sub>   | Rise Time                        |  |     | 71   |      | ns    |
| t <sub>D(OFF)</sub>  | Turn-Off Delay Time              | V <sub>GS</sub> =10V<br>R <sub>GEN</sub> = 6 ohm                   |     | 162  |      | ns    |
| t <sub>f</sub>   | Fall Time                        |  |     | 42   |      | ns    |
| Q <sub>g</sub>   | Total Gate Charge                | V <sub>DS</sub> =30V, I <sub>D</sub> =25A, V <sub>GS</sub> =10V    |     | 28   |      | nC    |
| Q <sub>gs</sub>  | Gate-Source Charge               | V <sub>DS</sub> =30V, I <sub>D</sub> =25A,<br>V <sub>GS</sub> =10V |     | 5    |      | nC    |
| Q <sub>gd</sub>  | Gate-Drain Charge                |  |     | 9.6  |      | nC    |
| <b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>                  |                                  |  |     |      |      |       |
| V <sub>SD</sub>  | Diode Forward Voltage            | V <sub>GS</sub> =0V, I <sub>S</sub> =2A                            |     | 0.78 | 1.3  | V     |
| <b>Notes</b>   |                                  |  |     |      |      |       |
| a.Surface Mounted on FR4 Board, t ≤ 10sec.                                     |                                  |  |     |      |      |       |
| b.Pulse Test:Pulse Width ≤ 300us, Duty Cycle ≤ 2%.                             |                                  |  |     |      |      |       |
| c.Guaranteed by design, not subject to production testing.                     |                                  |  |     |      |      |       |
| d.Starting T <sub>J</sub> =25°C, L=0.5mH, V <sub>DD</sub> = 30V.(See Figure13) |                                  |  |     |      |      |       |

Oct,13,2011

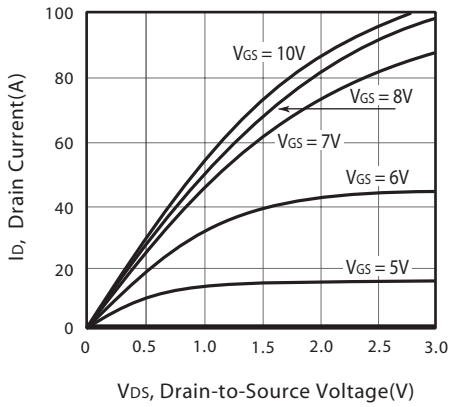


Figure 1. Output Characteristics

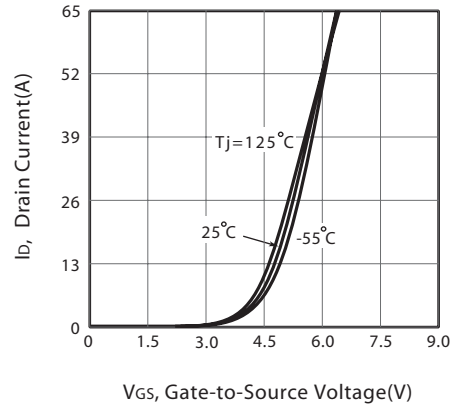


Figure 2. Transfer Characteristics

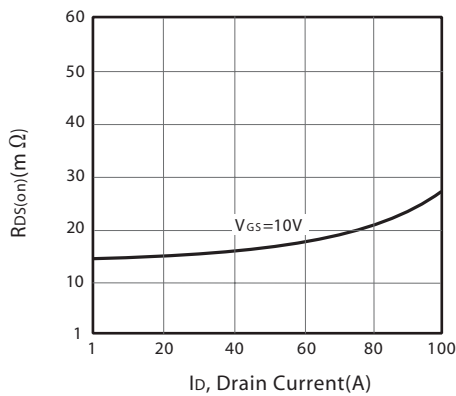


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

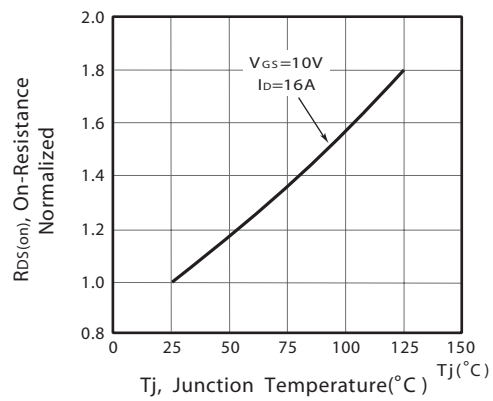


Figure 4. On-Resistance Variation with Drain Current and Temperature

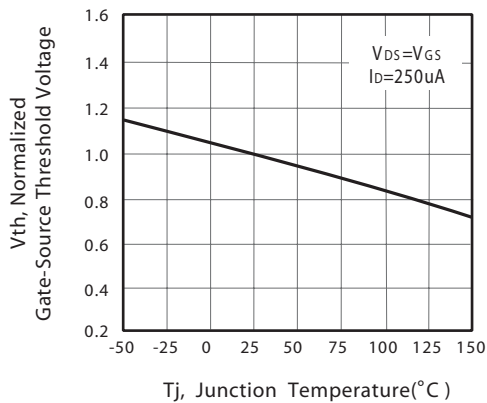


Figure 5. Gate Threshold Variation with Temperature

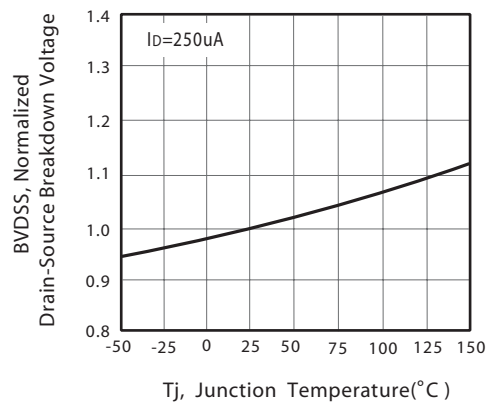


Figure 6. Breakdown Voltage Variation with Temperature

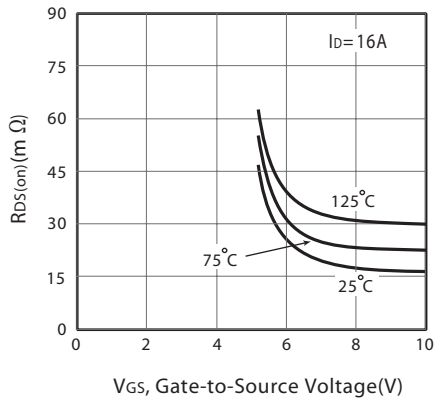


Figure 7. On-Resistance vs. Gate-Source Voltage

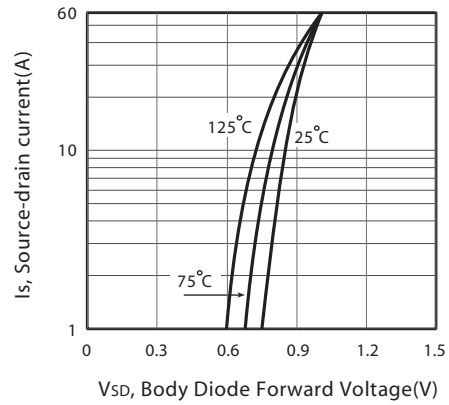


Figure 8. Body Diode Forward Voltage Variation with Source Current

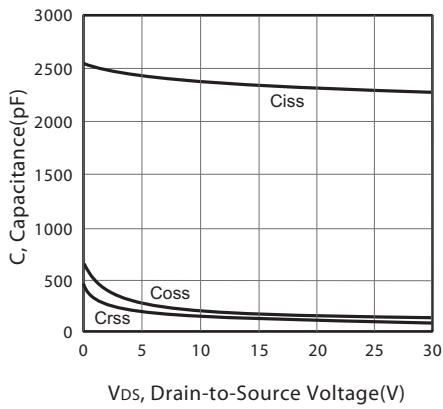


Figure 9. Capacitance

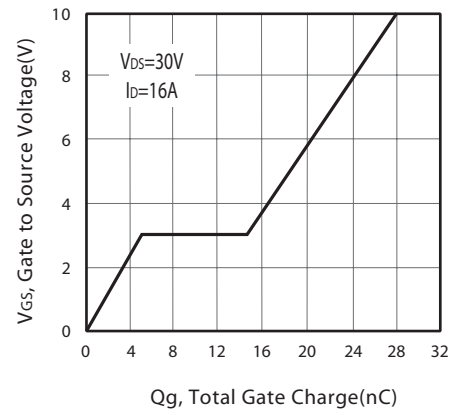


Figure 10. Gate Charge

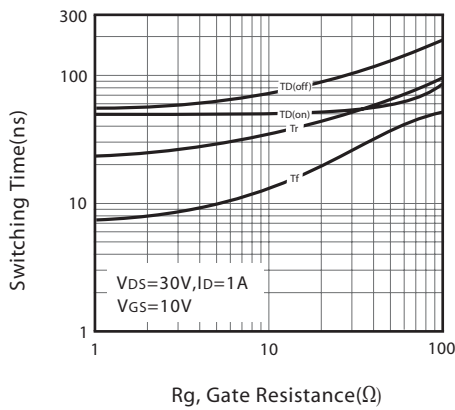


Figure 11. switching characteristics

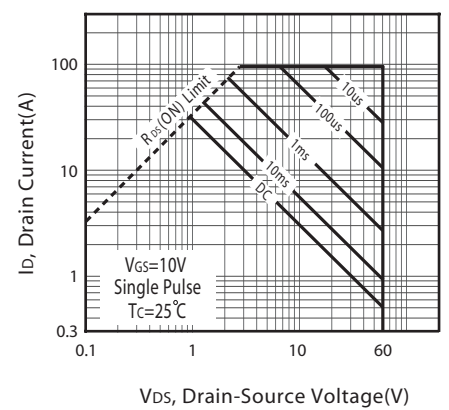
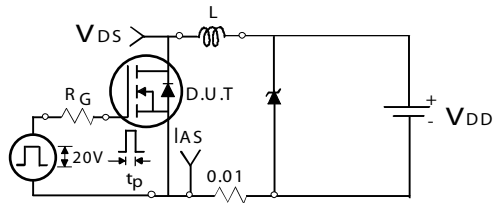


Figure 12. Maximum Safe Operating Area

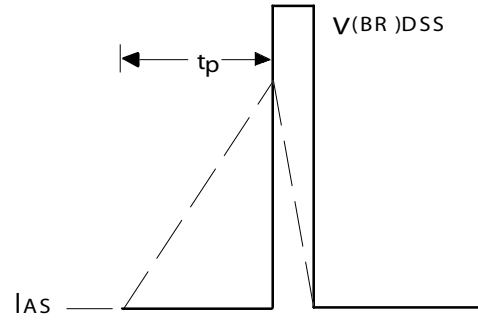
# STP60L60F

Ver 1.0



Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

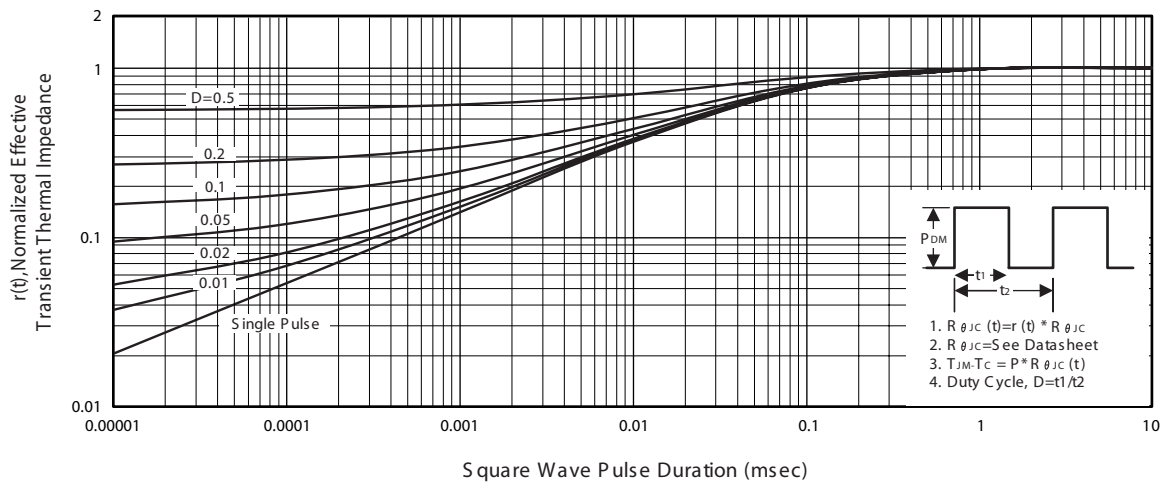


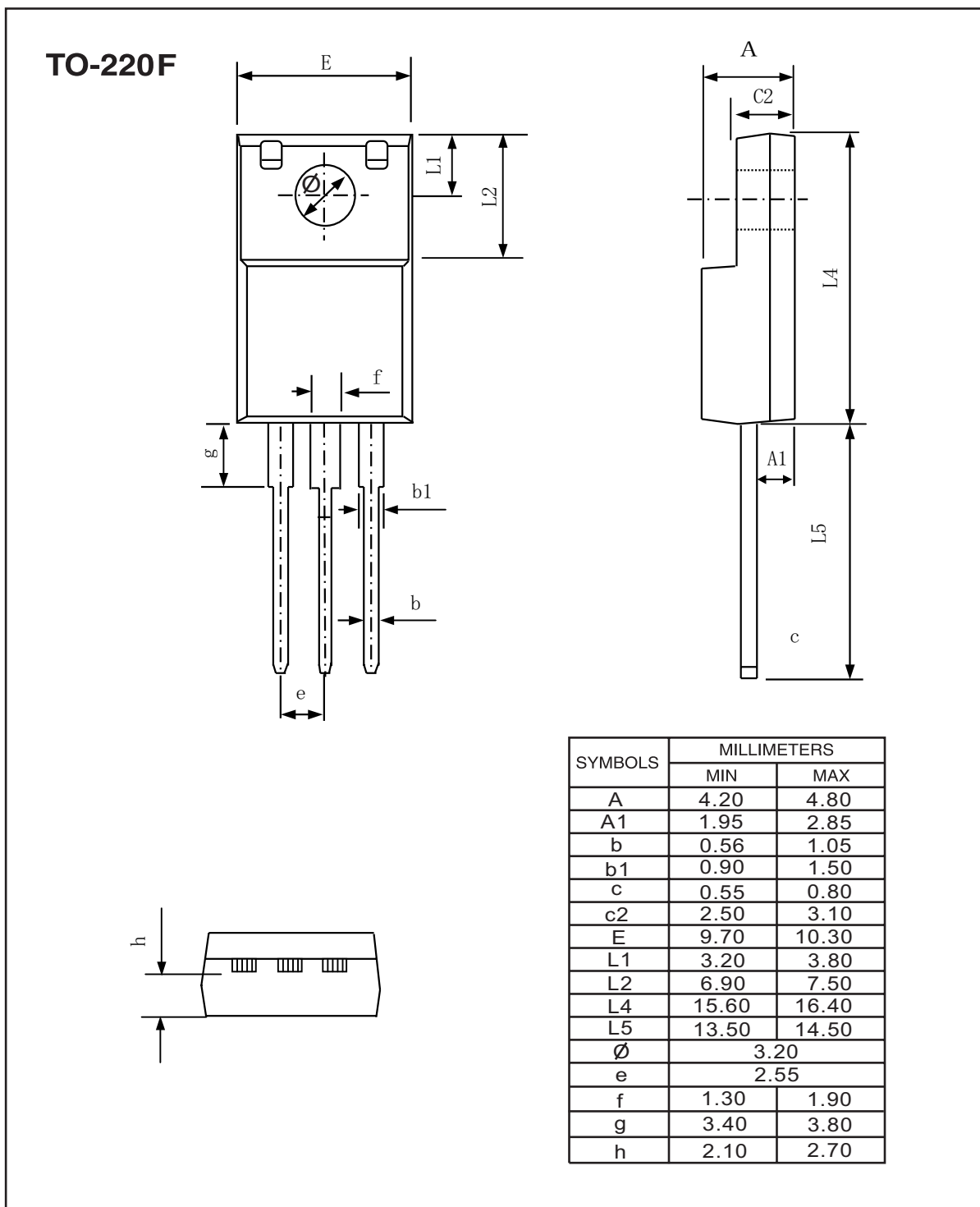
Figure 14. Normalized Thermal Transient Impedance Curve

Oct, 13, 2011

# STP60L60F

Ver 1.0

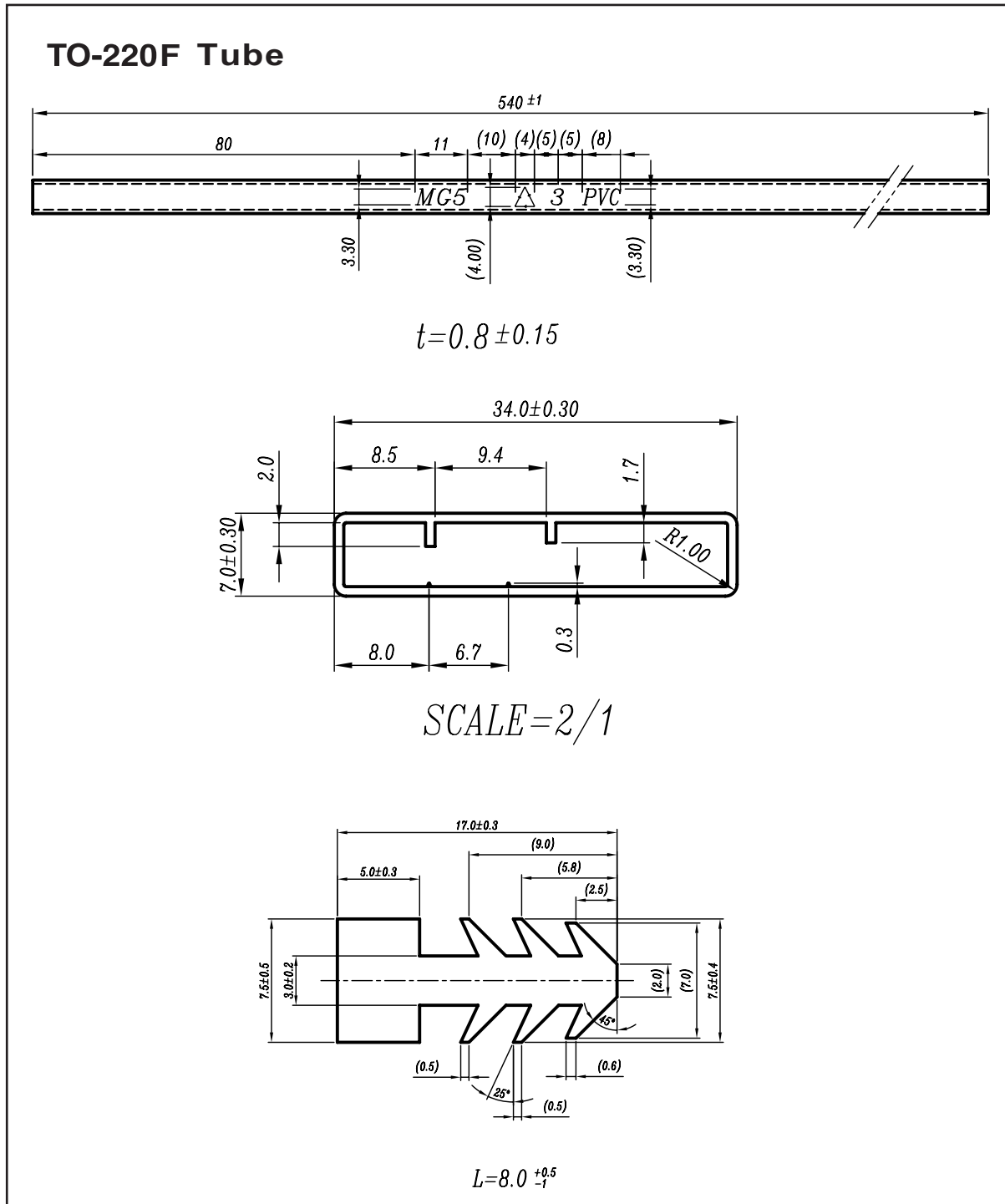
## PACKAGE OUTLINE DIMENSIONS



Oct,13,2011

# STP60L60F

Ver 1.0



Oct, 13, 2011